

EL 465852697

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**priority** Application Serial No. .... 09/389,844  
**priority** Filing Date ..... September 2, 1999  
Inventor ..... Salman Akram  
Assignee ..... Micron Technology, Inc.  
**priority** Group Art Unit ..... 2826  
**priority** Examiner ..... F. Abraham  
Attorney's Docket No. .... MI22-1572  
Title: Methods Of Forming Board-On-Chip Packages (as amended)

**PRELIMINARY AMENDMENT**

To: BOX NON-FEE AMENDMENT  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: David G. Latwesen, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)  
Wells, St. John, Roberts, Gregory & Matkin P.S.  
601 W. First Avenue, Suite 1300  
Spokane, WA 99201-3828

**AMENDMENTS**

**In the Specification**

Replace the title with,

--Methods Of Forming Board-On-Chip Packages--.

At p. 1, before the "Technical Field" section, insert

**--RELATED PATENT DATA**

This patent resulted from a divisional application of U.S. Patent Application Serial No. 09/389,844, which was filed on September 2, 1999.--.

**Amended Claims**

Cancel claims 1-41.

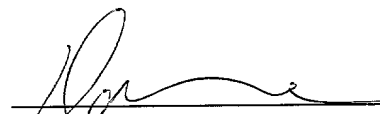
**REMARKS**

Claims 1-41 are canceled, leaving claims 42-74 pending in the application.  
Applicant requests substantive examination of pending claims 42-74 in the Examiner's next  
Action.

Respectfully submitted,

Dated: January 9, 2001

By: \_\_\_\_\_

  
David G. Latwesen, Ph.D.  
Reg. No. 38,533